



Material Content Data Sheet



Sales Product Name		BCM 846S H6327		Issued		20. July 2018		
MA#		MA000856910						
Package		PG-SOT363-6-1		Weight*		6.27 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.006	0.09		935	
	non noble metal	arsenic	7440-38-2	0.000	0.00		9	
	inorganic material	silicon	7440-21-3	0.050	0.80	0.89	7988	8932
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		92	
	non noble metal	titanium	7440-32-6	0.003	0.05		459	
	non noble metal	chromium	7440-47-3	0.009	0.14		1378	
	non noble metal	copper	7440-50-8	2.869	45.73	45.93	457399	459328
wire	non noble metal	copper	7440-50-8	0.010	0.17	0.17	1662	1662
encapsulation	organic material	carbon black	1333-86-4	0.031	0.49		4871	
	plastics	epoxy resin	-	0.657	10.47		104732	
	inorganic material	silicondioxide	60676-86-0	2.368	37.75	48.71	377521	487124
leadfinish	non noble metal	tin	7440-31-5	0.213	3.40	3.40	33993	33993
plating	noble metal	silver	7440-22-4	0.056	0.90	0.90	8961	8961
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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